



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-04-24
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	805(*M97GLQ2	A	SA1A	2013-04-24
Amount	UoM	Unit type	ST ECOPACK Grade	
24.05	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x0.95	5	No lead	
Comment	Package: DFN.30.30.10-095-6L-3E			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	805(*M97GLQ2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.478	mg		Silicon die	Silicon (Si)	7440-21-3		0.478	mg	1000000	19874
Lead frame	Copper & its alloys	7.921	mg		Alloy	Copper	7440-50-8		7.785	mg	982830	323687
Lead frame					Alloy	Chromium	7440-47-3		0.02	mg	2525	832
Lead frame					Alloy	Tin	7440-31-5		0.02	mg	2525	832
Lead frame					Alloy	Zinc	7440-66-6		0.017	mg	2146	707
Lead frame					Alloy	Silver	7440-22-4		0.079	mg	9973	3285
Die attach	Other Organic Materials	0.301	mg		Glue	Silver	7440-22-4		0.242	mg	803987	10062
Die attach					Glue	Carbocyclic Acrylates	Proprietary		0.03	mg	99668	1247
Die attach					Glue	Bismaleimide resin	Proprietary		0.009	mg	29900	374
Die attach					Glue	2-preponoic acid, 2-methyl	68586-19-6		0.009	mg	29900	374
Die attach					Glue	Additive	Proprietary		0.009	mg	29900	374
Die attach					Glue	Dicumyl peroxide	80-43-3		0.002	mg	6645	83
Bonding wire	Precious metals	0.29	mg		Bonding wire	Gold (Au)	7440-57-5		0.29	mg	1000000	12058
Encapsulation	Other Organic Materials	14.691	mg		Molding compound	Silica fused	60676-86-0		13.765	mg	936968	572325
Encapsulation					Molding compound	Epoxy resin	Proprietary		0.441	mg	30018	18336
Encapsulation					Molding compound	Phenol resin	Proprietary		0.441	mg	30018	18336
Encapsulation					Molding compound	Carbon black	1333-86-4		0.044	mg	2995	1829
Finishing	Other inorganic materials	0.37	mg		Connection coating	Sn	7440-31-5		0.37	mg	1000000	15384